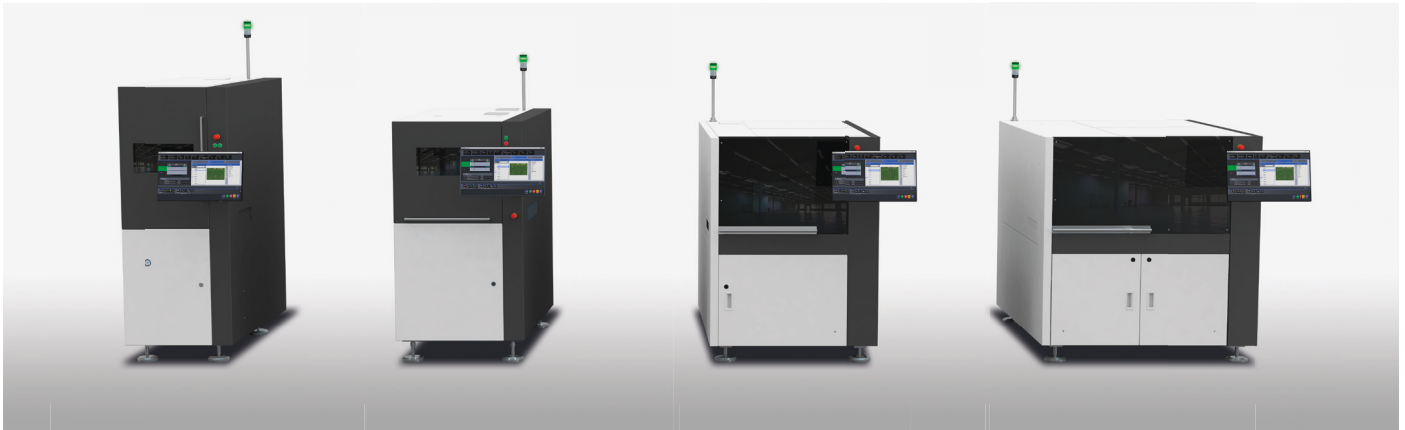


POLYPHOS SERIES – DP Laser-Depaneling

POLYPHOS SERIES – CT Laser-Cutting



ASYS Sets a New Standard in Laser Competence

ASYS provides a broad product line of depaneling solutions that range from semi-automatic to high-end inline systems.

The POLYPHOS CT 7000 and POLYPHOS DP 8000 and 9000 Series machines utilize the latest laser technology and are ergonomically designed with particular focus on reliability, easy operation and reduced footprint.

The **POLYPHOS CT 7000 Series** is a machine platform for laser cutting of metal core PCBs, respectively IMS (Integrated Metal Substrate) for e.g. LED luminaires or ceramic substrates like power semiconductors on DCB substrates. Unlike the POLYPHOS 8000 Series, the system consists of a CNC-controlled machine with a precision cutting head to position the laser beam. Cutting gas supports the cutting process. Depending on the application different gases can be used. A camera is used for machine calibration and offset correction using fiducials.

The **POLYPHOS DP 8000 Series** sets new standards in laser depaneling of rigid and flexible PCBs. A hard stone base allows for maximum stability and precision. Different beam sources are available to adapt to the material. The system is available as a stand-alone or fully automated inline system. For inline production various product specific carrier transport and systems are available. A camera is used for machine calibration and offset correction using fiducials. The system uses a precise XY-axis system and a digital galvo scanner for a Step&Scan process to optimize throughput and accuracy.

Features

- › High positioning accuracy
- › DIN language controlled (CNC) cutting recipes (POLYPHOS CT 7000 and DP 8x00)
- › State of the art beam sources and optics for improved cutting result
- › Graphic editor for cutting recipes (POLYPHOS DP 9000)

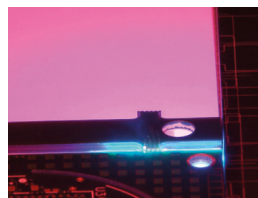
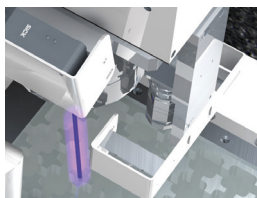
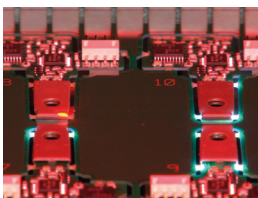
The **POLYPHOS DP 9000 Series** is a cost-effective and throughput-optimized laser depaneling system for the depaneling of electronic circuits with a thickness of up to 1.6mm. It enables flexible automation concepts thanks to various product carrier options and transport options. In addition, various working areas can be integrated to meet different panel size and accuracy requirements.

ASYS GROUP

Besuchen Sie unsere Website.
www.asys-group.com

Benefit from our services

- › High quality service team
- › 24 hour service hotline
- › Short reaction times
- › Worldwide maintenance service, operator and process trainings
- › Support via remote service
- › Worldwide service network



| POLYPHOS Series | | Model Overview and Options | | | | |
|--|------------------------|----------------------------|---------------------|---------------------|---------------------|-----------------------|
| | | POLYPHOS CT 7000 | POLYPHOS DP 8000 | POLYPHOS DP 8100 | POLYPHOS DP 8200 | POLYPHOS DP 9000 |
| Working area (max. LxW in mm) ¹ | | 490x460 | 305x250 | 460x305 | 460x460 | 180x180 up to 245x245 |
| Machine dimensions (LxWxH in mm) ¹ | | 830x1565x1550 | 1090x1800x1455 | 1400x1800x1570 | 1400x1900x1570 | 700x1548x1685 |
| Scan field | | | 50x50 up to 80x80 | 50x50 up to 80x80 | 50x50 up to 80x80 | 180x180 up to 245x245 |
| Galvo scanner | | | ✖ | ✖ | ✖ | ✖ |
| Cutting head | | ✖ | | | | |
| Noise Level | | < 75 dB(A) | < 75 dB(A) | < 75 dB(A) | < 75 dB(A) | < 75 dB(A) |
| NC Axes | | ✖ | | | | |
| DPSS-Laser with SHG | 30 W | | ✖ | ✖ | ✖ | ○ |
| | 40 W | | ○ | ○ | ○ | ✖ |
| UV-Laser | | | ○ | ○ | ○ | |
| CO ₂ -Laser | 150 W | | ○ | ○ | ○ | |
| QCW Fiber Laser | 150 W | ✖ | | | | |
| | 300 W | ○ | | | | |
| Laser-class | | 1 | 1 | 1 | 1 | 1 |
| Panel length (in mm) | | 20 to 508 | 20 to 305 | 20 to 460 | 20 to 460 | 20 to 360 / 20 to 400 |
| Panel width (in mm) | | 20 to 460 | 20 to 250 | 20 to 305 | 20 to 460 | 20 to 180 / 20 to 245 |
| Panel thickness (in mm) | | 0.1 to 1.6 (2.0) | 0.1 to 1.6 (2.0) | 0.1 to 1.6 (2.0) | 0.1 to 1.6 (2.0) | 0.1 to 1.6 (2.0) |
| MCPCB/IMS | QCW Fiber Laser | ✖ | | | | |
| Ceramic (AlN, Si ₃ N ₄ , Al ₂ O ₃) | QCW Fiber Laser | ✖ | | | | |
| FR4 1.6mm | DPSS-Laser with SHG | | ✖ | ✖ | ✖ | ✖ |
| Product-specific carrier and handling systems available | | | | | | |
| Ionisation | | ○ | ○ | ○ | ○ | ○ |
| Fiducial recognition | | ✖ | ✖ | ✖ | ✖ | ✖ |
| “Bad” mark recognition | | ○ | ○ | ○ | ○ | ○ |
| Code Read | | ○ | ○ | ○ | ○ | ○ |
| Hand-scanner | | ○ | ○ | ○ | ○ | ○ |
| Automatic scanner | | ○ | ○ | ○ | ○ | ○ |
| “Good/bad” interface | | ○ | ○ | ○ | ○ | ○ |
| Prod. data management | | ○ | ○ | ○ | ○ | ○ |
| Traceability function | | ○ | ○ | ○ | ○ | ○ |
| Segment conveyor | | ○ | ○ | ○ | ○ | ○ |
| Carrier transport | | ○ | ○ | ○ | ○ | ○ |
| Sliding cover | | ✖ | ✖ | ✖ | ✖ | |
| Technical availab. ≥ 98 % | | ○ | ○ | ○ | ○ | ○ |
| CE declaration | | ✖ | ✖ | ✖ | ✖ | ✖ |
| MFU | | ✖ | ✖ | ✖ | ✖ | ✖ |
| Sound pressure test | | ✖ | ✖ | ✖ | ✖ | ✖ |
| Stress tests | | ○ | ○ | ○ | ○ | ○ |
| Process capability tests | | ○ | ○ | ○ | ○ | ○ |

✗ Standard
○ Option

¹ Other dimensions on request

MFU = Machine capability study

Subject to change without notice. Some general descriptions and performance characteristics may not be applicable to all products. Technical specifications are subject to change without notice.Only features and technical data provided in purchasing contract are legally binding. Printed in Germany